SOT1113-3

HVQFN44, plastic, thermal enhanced very thin quad flatpack; no leads; 44 terminals; 0.65 mm pitch; 9 mm x 9 mm x 1 mm body

30 April 2019 | Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN44
Package type industry code	HVQFN44
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-04-2019
Manufacturer package code	98ASA10742D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	9	-	mm
package width	-	9	-	mm
package height	-	1	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	44	-	

2 Package outline

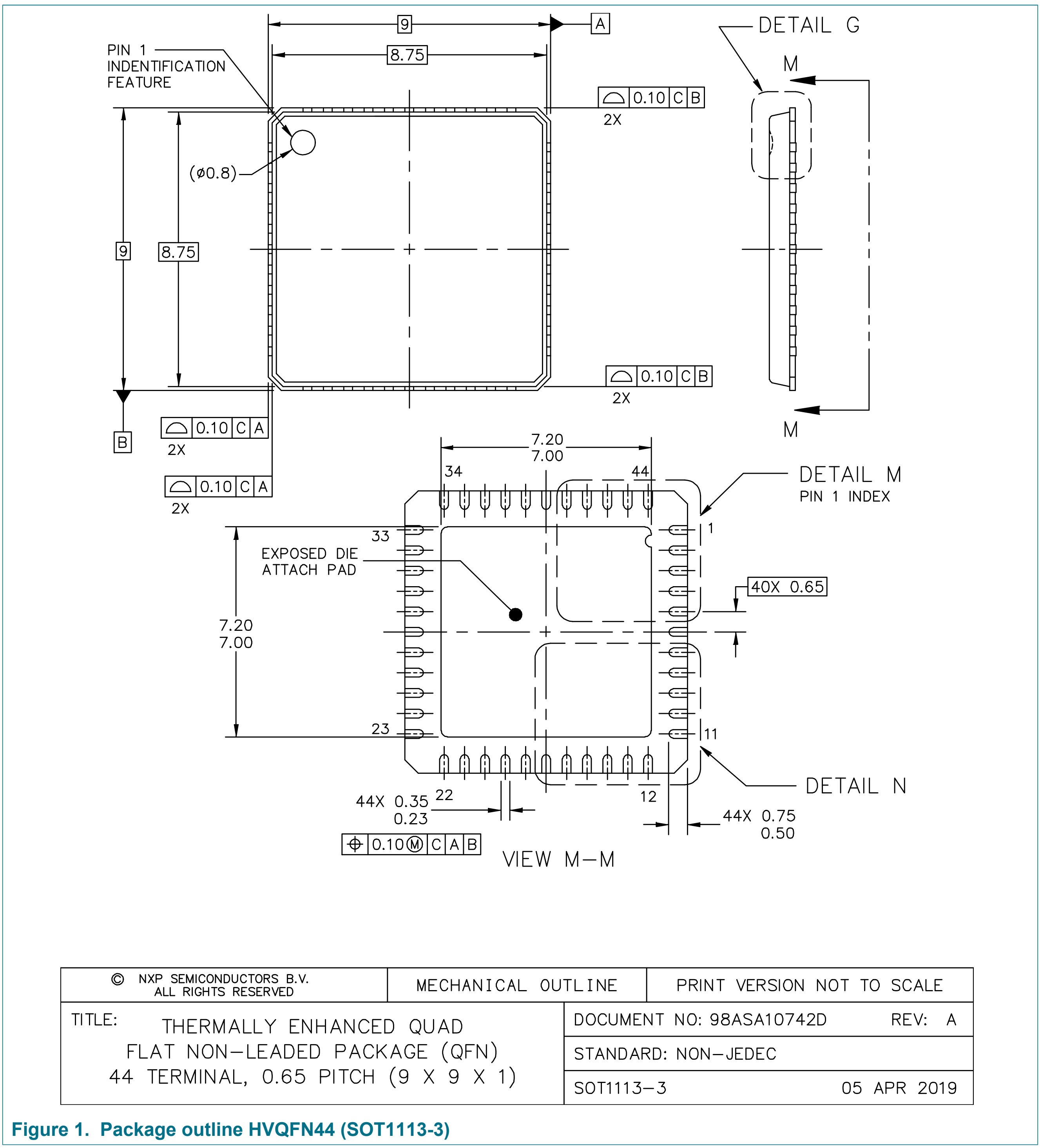

Figure 1. Package outline HVQFN44 (SOT1113-3)

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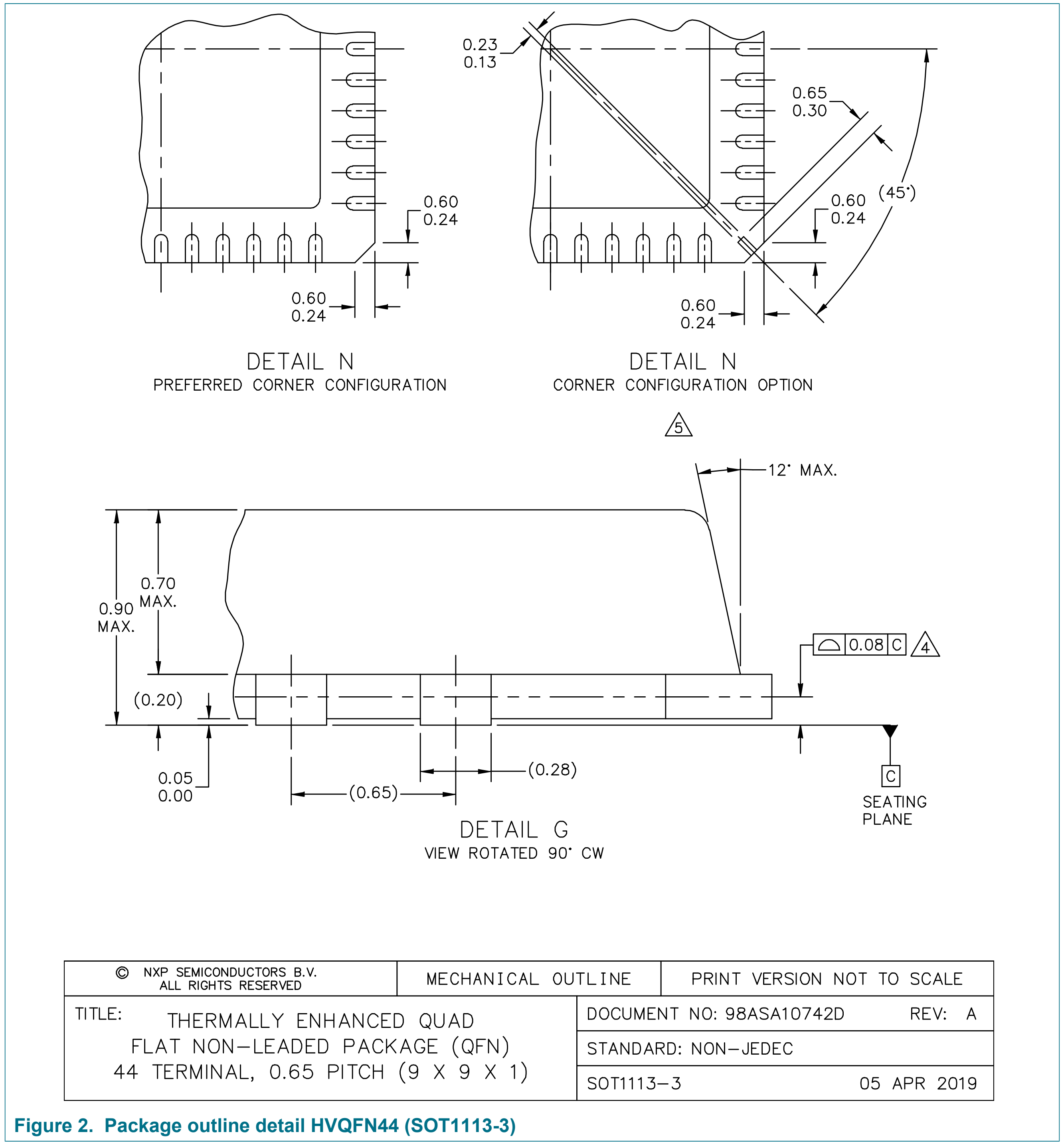

Figure 2. Package outline detail HVQFN44 (SOT1113-3)

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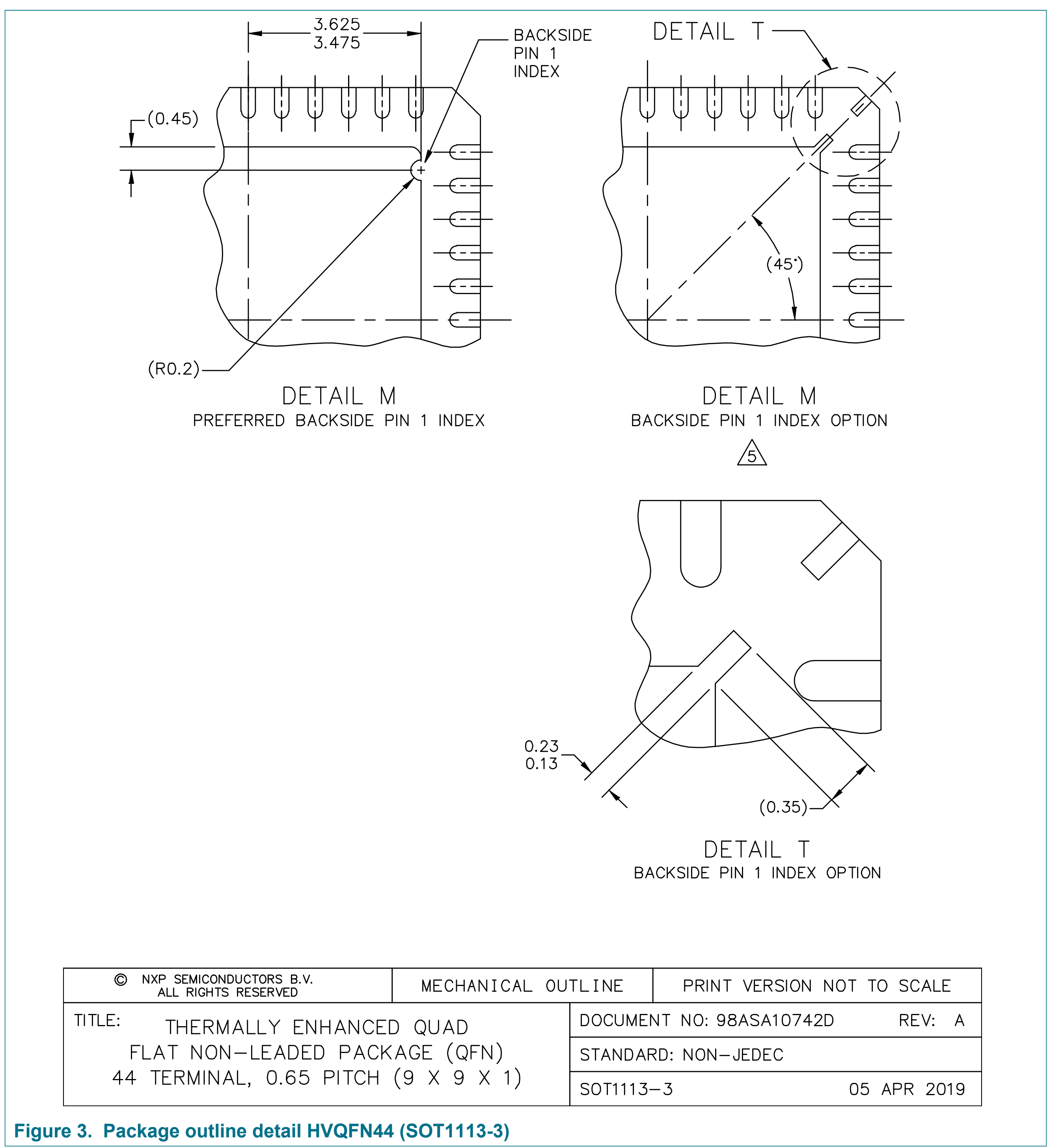

Figure 3. Package outline detail HVQFN44 (SOT1113-3)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF–PQFN.
4. COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD.
5. DIMENSIONS OF OPTIONAL FEATURES ARE FOR REFERENCE ONLY.
6. FOR ANVIL SINGULATED QFN PACKAGES, MAXIMUM DRAFT ANGLE IS 12°.
7. MIN METAL GAP SHOULD BE 0.25MM.

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TITLE: THERMALLY ENHANCED QUAD FLAT NON–LEADED PACKAGE (QFN) 44 TERMINAL, 0.65 PITCH (9 X 9 X 1)	DOCUMENT NO: 98ASA10742D	REV: A
	STANDARD: NON–JEDEC	
	SOT1113–3	05 APR 2019

Figure 4. Package outline note HVQFN44 (SOT1113-3)

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